Variant:
 001

 Generated:
 3/10/2015 5:57:33 PM

 SVN path:
 \$URL::

 SVN rev:
 \$Rev::

PMP9495

			T	1			I	
Designator !PCB	Quantity	Value	Printed Circuit Board	PackageReference	PartNumber SV601130	Manufacturer Any	Alternate PartNumber	Alternate Manufacturer
C1	1	68uF	CAP, AL, 68uF, 63V, +/-20%, 0.028 ohm, SMD	2-Pin SMD, Body 10.3 x 10.3 mm, Height 10	PCR1J680MCL1GS	Nichicon	-	-
C2, C3, C4,	5	4.7uF	CAP, CERM, 4.7uF, 100V, +/-10%, X7S, 1210	mm 1210	C3225X7S2A475K200A	TDK		
C5, C6 C7, C8, C9,	5	10uF	CAP, CERM, 10uF, 50V, +/-10%, X7R, 1210	1210	B GRM32ER71H106KA12	MuRata		
C10, C11 C12, C13	2	3.3uF	CAP, CERM, 3.3uF, 50V, +/-10%, X7R, 1206	1206	L C3216X7r1H335K160A	TDK		
					С			
C14, C15 C16, C17	2	180µF 100pF	ALUM SMD CAP 50 180UF 20%  CAP, CERM, 100pF, 100V, +/-5%, C0G/NP0, 1206	Radial, Can - SMD 1206	PCR1H181MCL1GS 12061A101JAT2A	Nichicon AVX	-	-
C19, C23,	5	0.1uF	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603	0603	GRM188R72A104KA35	MuRata		
C25, C27, C32			, , , , , , , , , , , , , , , , , , , ,		D			
C20	1	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603L	GRM188R71E105KA12 D	MuRata		
C21, C24	2	47pF	CAP, CERM, 47pF, 50V, +/-5%, C0G/NP0, 0603	0603L	GRM1885C1H470JA01 D	MuRata		
C22 C26	1 1	0.01uF 1000pF	CAP, CERM, 0.01 μF, 100 V, +/- 10%, X7R, 0603 CAP, CERM, 1000 pF, 25 V, +/- 10%, X7R, 0603	0603 0603	06031C103KAT2A GRM188R71E102KA01	AVX MuRata		
		Гооорг			D			
C28 C29	1 1	0.022uF	RES, 0 ohm, 5%, 0.1W, 0603 CAP, CERM, 0.022uF, 50V, +/-10%, X7R, 0603	0603 0603	RC0603JR-070RL C0603C223K5RACTU	Yageo America Kemet		
C30, C31,	3	100pF	CAP, CERM, 0.022uF, 50V, +/-10%, X7R, 0603 CAP, CERM, 100pF, 100V, +/-5%, C0G/NP0, 0603	0603L	GRM1885C2A101JA01	MuRata		
C33	1	20V	Diode, Schottky, 20V, 1A, SMA	SMA	D SS12-E3/61T	Vishay-Semiconductor		
D2	1	60V	Diode, Schottky, 60V, 3A, SMA	SMA	B360A-13-F	Diodes Inc.		
D3	1	60V	Diode, Schottky, 60 V, 1 A, SOD-123F	SOD-123F	PMEG6010CEH,115	NXP Semiconductor		
D4, D5	2	100V	Diode, Ultrafast, 100V, 0.25A, SOD-323	SOD-323	BAS316,115	NXP Semiconductor		
H1, H2, H3, H4	4		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead		NY PMS 440 0025 PH	B&F Fastener Supply	-	-
H5, H6, H7, H8	4		Standoff, Hex, 0.5"L #4-40 Nylon	Standoff	1902C	Keystone	-	-
J1, J2, J5, J6	4		TEST POINT SLOTTED .118", TH	Test point, TH Slot Test point	1040	Keystone		
J3, J4, J7, J8	4		Standard Banana Jack, Uninsulated, 15A	Banana Jack	108-0740-001	Emerson Network Power		
J9	1	1x3	Header, TH, 100mil, 1x3, Gold plated, 230 mil above insulator	PBC03SAAN	PBC03SAAN	Sullins Connector Solutions		
L1	1	4.7uH	Inductor, Shielded, Composite, 4.7uH, 29A, 0.00335 ohm, SMD	15.4 x 11 x 16.4mm	XAL1510-472MEB	Coilcraft		
Q1, Q2	2	60V	MOSFET, N-CH, 60 V, 19 A, SON 5x6mm	SON 5x6mm	CSD18531Q5A	Texas Instruments		None
Q3, Q4	1	30V	MOSFET, N-CH, 30 V, 100 A, SON 5x6mm	SON 5x6mm 2512 WIDE	CSD17573Q5B RCL12250000Z0EG	Texas Instruments Vishay Draloric		None
R1 R2	1	0.009	RES, 0 ohm, 5%, 2W, 2512 WIDE RES, 0.009, 1%, 4 W, 3015 WIDE	3015 WIDE	KRL7638-C-R009-F-T1	Susumu Co Ltd		
R3, R8	2	10.0	RES, 10.0 ohm, 1%, 0.25W, 1206	1206	RC1206FR-0710RL	Yageo America		
R5, R6, R10, R11, R14, R27, R28	7	0	RES, 0 ohm, 5%, 0.1W, 0603	0603L	RC0603JR-070RL	Yageo America		
R13	1	249k	RES, 249k ohm, 1%, 0.1W, 0603	0603	RC0603FR-07249KL	Yageo America		
R15	1	0.008	RES, 0.008, 1%, 4 W, 3015 WIDE	3015 WIDE	KRL7638-C-R008-F-T1	Susumu Co Ltd		
R16	1	59.0k	RES, 59.0k ohm, 1%, 0.1W, 0603	0603L	RC0603FR-0759KL	Yageo America		
R17, R34	2	10.0	RES, 10.0 ohm, 1%, 0.1W, 0603	0603L	RC0603FR-0710RL	Yageo America		<u> </u>
R19, R22, R25, R26	4	100	RES, 100 ohm, 1%, 0.1W, 0603	0603L	RC0603FR-07100RL	Yageo America		
R23, R29 R24	1	10.0k 93.1k	RES, 10.0k ohm, 1%, 0.1W, 0603 RES, 93.1k ohm, 1%, 0.1W, 0603	0603L 0603	RC0603FR-0710KL RC0603FR-0793K1L	Yageo America Yageo America		
R24 R30	1	17.8k	RES, 17.8 k, 1%, 0.1 W, 0603	0603	CRCW060317K8FKEA	Vishay-Dale		
R31	1	84.5k	RES, 84.5 k, 1%, 0.1 W, 0603	0603	RC0603FR-0784K5L	Yageo America		
R33	1	280k	RES, 280k ohm, 1%, 0.1W, 0603	0603L	RC0603FR-07280KL	Yageo America		
TP1	1	Red	Test Point, Compact, Red, TH	Red Compact Testpoint	5005	Keystone		
TP2	1	Yellow	Test Point, Compact, Yellow, TH	Yellow Compact Testpoint	5009	Keystone		
TP3, TP5	2	Orange	Test Point, Compact, Orange, TH	Orange Compact Testpoint	5008	Keystone		
TP4	1	White	Test Point, Compact, White, TH	White Compact Testpoint	5007	Keystone		
U1	1		42V Wide VIN 4-Switch Synchronous Buck-Boost Controller, PWP0028F	PWP0028F	LM5175PWPR	Texas Instruments	LM5175PWPT	Texas Instruments
C18	0	47pF	CAP, CERM, 47pF, 50V, +/-5%, C0G/NP0, 0603	0603L	GRM1885C1H470JA01 D	MuRata		
C34	0		CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	Used in PnP output	Used in BOM report	Used in BOM report	-	-
FID1, FID2, FID3	0		Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A		
			TEST POINT SLOTTED .118", TH	Test point, TH Slot	1040	Keystone		
J10, J11	0			Test point				
R18, R21	0	100	RES, 100 ohm, 1%, 0.1W, 0603	0603	RC0603FR-07100RL	Yageo America		
		100 240k			RC0603FR-07100RL RC0603FR-07240KL Used in BOM report	Yageo America Yageo America Used in BOM report		

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

## IMPORTANT NOTICE FOR TI REFERENCE DESIGNS

Texas Instruments Incorporated ("TI") reference designs are solely intended to assist designers ("Buyers") who are developing systems that incorporate TI semiconductor products (also referred to herein as "components"). Buyer understands and agrees that Buyer remains responsible for using its independent analysis, evaluation and judgment in designing Buyer's systems and products.

TI reference designs have been created using standard laboratory conditions and engineering practices. TI has not conducted any testing other than that specifically described in the published documentation for a particular reference design. TI may make corrections, enhancements, improvements and other changes to its reference designs.

Buyers are authorized to use TI reference designs with the TI component(s) identified in each particular reference design and to modify the reference design in the development of their end products. HOWEVER, NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY THIRD PARTY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT, IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI REFERENCE DESIGNS ARE PROVIDED "AS IS". TI MAKES NO WARRANTIES OR REPRESENTATIONS WITH REGARD TO THE REFERENCE DESIGNS OR USE OF THE REFERENCE DESIGNS, EXPRESS, IMPLIED OR STATUTORY, INCLUDING ACCURACY OR COMPLETENESS. TI DISCLAIMS ANY WARRANTY OF TITLE AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, QUIET ENJOYMENT, QUIET POSSESSION, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS WITH REGARD TO TI REFERENCE DESIGNS OR USE THEREOF. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY BUYERS AGAINST ANY THIRD PARTY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON A COMBINATION OF COMPONENTS PROVIDED IN A TI REFERENCE DESIGN. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, SPECIAL, INCIDENTAL, CONSEQUENTIAL OR INDIRECT DAMAGES, HOWEVER CAUSED, ON ANY THEORY OF LIABILITY AND WHETHER OR NOT TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES, ARISING IN ANY WAY OUT OF TI REFERENCE DESIGNS OR BUYER'S USE OF TI REFERENCE DESIGNS.

TI reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques for TI components are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

Reproduction of significant portions of TI information in TI data books, data sheets or reference designs is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards that anticipate dangerous failures, monitor failures and their consequences, lessen the likelihood of dangerous failures and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in Buyer's safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed an agreement specifically governing such use.

Only those TI components that TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have *not* been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.